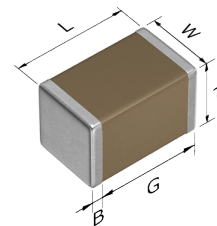


积层贴片陶瓷片式电容器

C2012X7R1E225K085AB

RoHS Reach Halogen Free Pb Free

| | |
|------|-------------------------------------------------------|
| 交货型号 | C2012X7R1E225KT**** |
| 用途 | 一般等级 车载用途时为 CGA4J3X7R1E225K125AB 。 |
| 特点 | General 一般 (~75V) |
| 系列 | C2012 [EIA 0805] |
| 状态 | 量产体制(新设计非推荐) |



尺寸

| | |
|------------|------------------------------------------------------------------------|
| 长度(L) | 2.00mm ±0.20mm |
| 宽度(W) | 1.25mm ±0.20mm |
| 厚度(T) | 0.85mm ±0.15mm |
| 端子宽度(B) | 0.20mm Min. |
| 端子间隔(G) | 0.50mm Min. |
| 推荐焊盘布局(PA) | 1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering) |
| 推荐焊盘布局(PB) | 1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering) |
| 推荐焊盘布局(PC) | 0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering) |

电气特性

| | |
|-------------|-------------|
| 电容 | 2.2 μF ±10% |
| 额定电压 | 25VDC |
| 温度特性 | X7R(±15%) |
| 耗散因数 (Max.) | 5% |
| 绝缘电阻 (Min.) | 227MΩ |

其他

| | |
|----------|---------------|
| 焊接方法 | 流体 回流 |
| AEC-Q200 | NO |
| 包装形式 | 纸编带 (180mm卷筒) |
| 包装个数 | 4000pcs |

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

特性图表 (这是参考数据，并不保证产品的特性。)

Associated Images

